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N-Channel Super Junction Power MOSFET $\, \mathrm{I\!V}$

General Description

The series of devices use advanced trench gate super junction technology and design to provide excellent R_{DS(ON)} with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

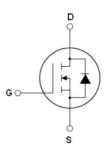
Feature:	S
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- New technology for high voltage device
- ●Low on-resistance and low conduction losses
- Small package
- ●Ultra Low Gate Charge cause lower driving requirements
- ●100% Avalanche Tested
- ROHS compliant

Application

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)

V _{DS min@Tjmax}	550	V
R _{DS(ON)TYP} .	460	mΩ
I_D	7.2	Α
Qg	10	nC



Schematic diagram

♦ Intrinsic fast-recovery body diode

Package Marking And Ordering Information

Device	Device Package	Marking
NCE50NF520K	TO-252-2L	NCE50NF520K



TO-252

Table 1. Absolute Maximum Ratings (T_C=25℃)

Parameter	Symbol	Value	Unit
Drain-Source Voltage (Vgs=0V)	V _{DS}	500	V
Gate-Source Voltage (V _{DS=0} V) ,AC (f>1 Hz)	V _G s	±30	V
Gate-Source Voltage (V _{DS} =0V) ,DC	V _G s	±20	V
Continuous Drain Current at Tc=25°C	I _{D (DC)}	7.2	Α
Continuous Drain Current at Tc=100°C	I _{D (DC)}	5.04	Α
Pulsed drain current (Note 1)	I _{DM (pluse)}	21.6	Α
Maximum Power Dissipation(Tc=25℃)	P _D	73	W
Derate above 25°C		0.48	W/°C
Single pulse avalanche current (Note 2)	I _{AS}	2.5	Α
Reverse diode dv/dt, $V_{DS} \leq 480 \text{ V,I}_{SD} < I_{D}$	dv/dt	15	V/ns
Drain Source voltage slope,V _{DS} ≤480 V	dv/dt	50	V/ns
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55+175	°C

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Table 2. Thermal Characteristic

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R _{thJC}	2.05	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R _{thJA}	62	°C /W

Table 3. Electrical Characteristics (TA=25^oCunless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
On/off states			•			
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250uA	500			V
Zero Gate Voltage Drain Current(Tc=25°ℂ)	I _{DSS}	V _{DS} =500V,V _{GS} =0V			10	μA
Zero Gate Voltage Drain Current(Tc=125℃)	I _{DSS}	V _{DS} =500V,V _{GS} =0V			300	μA
Gate-Body Leakage Current	I _{GSS}	$V_{GS}=\pm20V, V_{DS}=0V$			±200	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS},I_{D}=250uA$	3		5	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =3.5A		460	520	mΩ
Dynamic Characteristics						
Gate Resistance	Rg	F=1MHZ, D-S short		55		Ω
Input Capacitance	C _{iss}	., 50,414 014		354		pF
Output Capacitance	Coss	V_{DS} =50V, V_{GS} =0V,		20		pF
Reverse Transfer Capacitance	C _{rss}	F=1MHz		4.7		pF
Total Gate Charge	Qg			10		nC
Gate-Source Charge	Q _{gs}	V_{DS} =380 V , I_{D} =3.5 A ,		4.5		nC
Gate-Drain Charge	Q _{gd}	V _{GS} =10V		2.6		nC
Gate plateau voltage	Vgp			7.2		V
Switching times				•		
Turn-on Delay Time	t _{d(on)}			8		nS
Turn-on Rise Time	tr	V_{DD} =380 V , I_{D} =4 A ,		10		nS
Turn-Off Delay Time	t _{d(off)}	$R_G=4\Omega, V_{GS}=10V$		41		nS
Turn-Off Fall Time	t _f			9		nS
Source- Drain Diode Characteristics			•			
Source-drain current(Body Diode)	I _{SD}	T 0500			7.2	Α
Pulsed-Source-drain current(Body Diode)	I _{SDM}	T _C =25°C			21.6	Α
Forward on voltage	V _{SD}	Tj=25°C,I _{SD} =7.2A,V _{GS} =0V		1.0	1.2	V
Reverse Recovery Time	t _{rr}			105		nS
Reverse Recovery Charge	Q _{rr}	Tj=25°C,lF4A,		0.42		uC
Peak reverse recovery current	I _{rrm}	di/dt=100A/µs		7.5		Α

Notes: 1. Repetitive Rating: Pulse width limited by maximum junction temperature

2. Tj=25 $^{\circ}\text{C}$,VDD=50V,VG=10V, RG=25 Ω



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure 1. Safe operating area

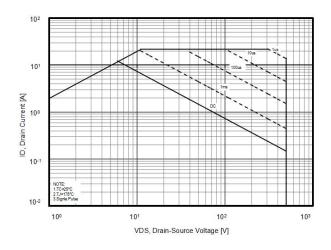


Figure 3. Output characteristics

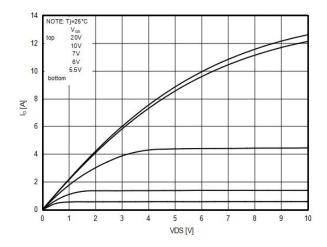


Figure 5. Static drain-source on resistance

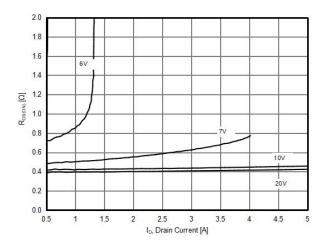


Figure2. Source-Drain Diode Forward Voltage

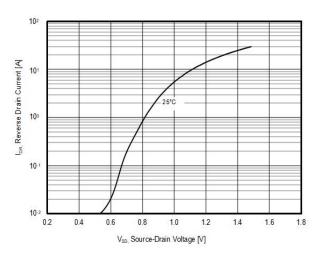


Figure 4. Transfer characteristics

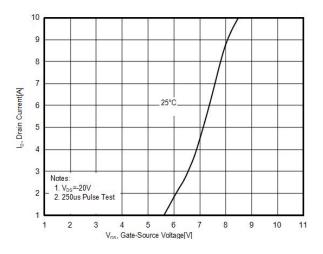
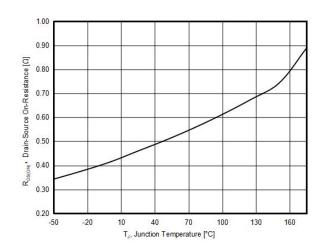


Figure 6. RDS(ON) vs Junction Temperature



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Figure 7. BV_{DSS} vs Junction Temperature

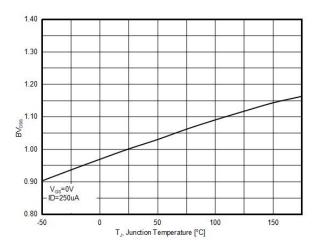


Figure 8. Maximum ID vs Junction Temperature

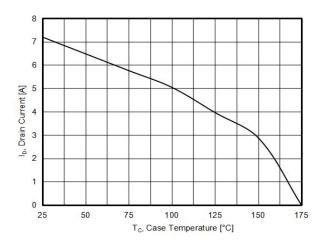


Figure 9. Gate charge waveforms

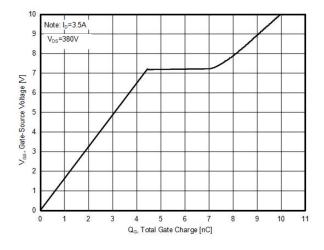
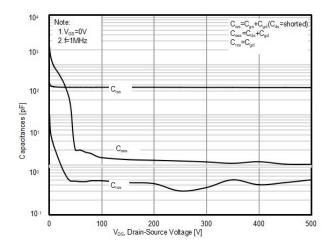


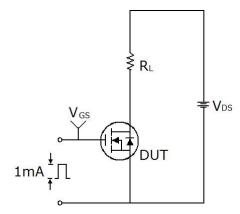
Figure 10. Capacitance

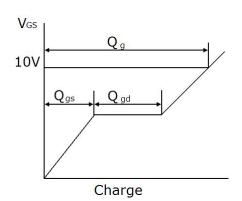




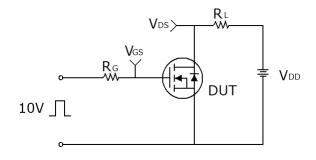
Test circuit

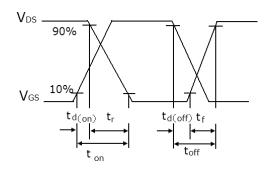
1) Gate charge test circuit & Waveform



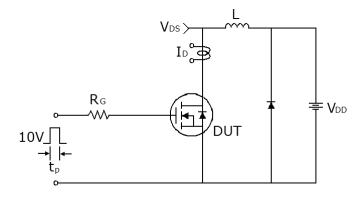


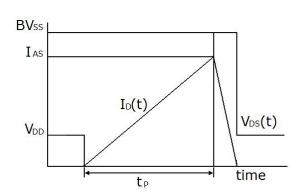
2) Switch Time Test Circuit:





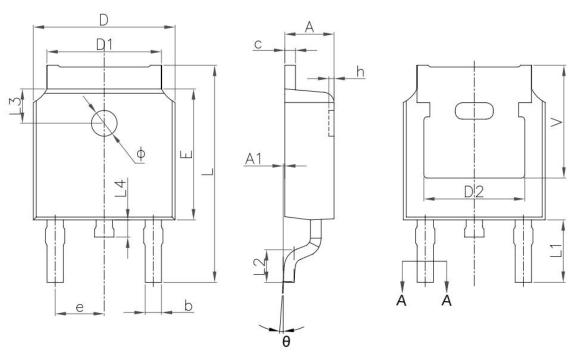
3) Unclamped Inductive Switching Test Circuit & Waveforms







TO-252-E Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
А	2.20	2.40	0.087	0.094	
A1	0.00	0.13	0.000	0.005	
b	0.66	0.86	0.026	0.033	
b1	0.73	0.79	0.029	0.031	
С	0.46	0.58	0.018	0.023	
c1	0.50	0.52	0.020	0.020	
D	6.50	6.70	0.256	0.264	
D1	5.10	5.46	0.201	0.215	
D2	4.83	REF	0.19REF		
Е	6.00	6.20	0.236	0.244	
е	2.19	2.39	0.086	0.094	
L	9.80	10.40	0.386	0.409	
L1	2.90	2.90 REF		REF	
L2	1.40	1.70	0.055		
L3	1.60	1.60 REF		REF	
L4	0.60	1.00	0.024	0.039	
Ф	1.10	1.30	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.00	0.30	0.000	0.012	



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